

Product / Process Change Notification JLIO-7NGMXY

The information below reflects a change that is being implemented.

Notice Date: 01/22/2009
Product Category: Power Management
Notification Subject: CCB#858: QUALIFICATION OF NEW WAFER
FAB FOUNDRY X-FAB FOR MCP1790,
MCP200x, and MCP2551 Products

Notification Body:

PCN Status:
Initial notification

Microchip Part#s Affected (please see the link for these files at the end of this PCN):

See attachment of Affected package/device in Qualification plan.

[CCB#858_Microchip_Catalog_Part#s_Affected.xls](#)

[CCB#858_Microchip_Catalog_Part#s_Affected.pdf](#)

Description of Change:
New Wafer Fab Foundry

Impacts to Data Sheet:
None

Reason for Change:
To improve production cycle time and on-time delivery performance

Change Implementation Status:
In Progress

Estimated Change Implementation Date(s):
February 20th, 2009 (Date Code: 0908)

Markings to Distinguish Revised from Unrevised Devices: (e.g.: Date Code,
Device Marking, Ship Container Marking)
Traceability code



MICROCHIP

QUALIFICATION PLAN

CCB#: 858
PCN#: JLIO-7NGMXY

Date:
November 20, 2008

Qualification of New Wafer Fab Foundry X-Fab for MCP1790, MCP200x, and MCP2551 Products

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Purpose: _____ Qualification of New Wafer Fab Foundry X-Fab for
MCP1790, MCP200x, and MCP2551 Products

Mask: _____ VKAA1, VKAA2, VKAB0, VKAB1, VK001

Part No.: _____ MCP1790, MCP2003, MCP2004, MCP2551

Reliability Test plan: _____ **See attached**

Process Reliability Tests								
Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Quantity of Lots	Total Units	Fail Accept #	Est. Dur. Days	Special Instructions
ELFR	+125°C for 48 hours; Electrical test pre and post stress at +25°C and 125°C.	800	80	1	880	0	7	Spares should be properly identified.
HTO/DLT	+125°C for 1008 hours; Electrical test pre and Post stress at -40, +25, and +125°C, Readouts at 0, 168, and 1008 hours	600	60	1	660	0	30	Spares should be properly identified.
ESD-HBM	Electrical test pre and Post stress at +25, and +125°C. Test at each voltage: 500V, 1kV, 2kV, 4kV.	12	0	1	12	0	5	3 devices per voltage level. Passing Criteria is ≥ 2 kV.
ESD - MM	Electrical test pre and post stress at +25 and +125 °C. Test at each voltage: 100V, 200V, 300V, 400V	12	0	1	12	0	5	3 devices per voltage level. Passing criteria is ≥ 200 V.
ESD-CDM	B. Tested per ESDA STM 5.3.1-1999 - 125V, 250V, 500V, 1000V, 1500V, 2000V	18	0	2	36	0	5	Spares should be properly identified.
Latch up		12	0	1	12	0	5	Spares should be properly identified.

Microchip_Catalog_Part#s

MCP1790T-5002E/EB
MCP1790-5002E/EB
MCP1790T-3302E/DB
MCP1790-3302E/DB
MCP1790T-3302E/EB
MCP1790-3302E/EB
MCP1790T-5002E/DB
MCP1790-5002E/DB
MCP1790T-3002E/DB
MCP1790-3002E/DB
MCP1790T-3002E/EB
MCP1790-3002E/EB
MCP2003
MCP2004
MCP2551T-I/SNA21
MCP2551-I/SNA21
MCP2551T-E/SNG
MCP2551T-I/SNG
MCP2551-I/SNG
MCP2551-E/SNG
MCP2551T-I/SN
MCP2551T-E/SN
MCP2551-I/SN
MCP2551-I/P
MCP2551-E/SN
MCP2551-E/P